



SOT1373-1

plastic thermal enhanced thin shrink small outline package;
32 leads; body width 6.1 mm; lead pitch 0.65 mm; exposed
die pad

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOT1373
Package type industry code	HTSSOP32
Package style descriptive code	HTSSOP (thermal enhanced thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-5-2014

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.9	-	5	5.1	mm
E	package width		3.4	-	3.5	3.6	mm
A	seated height		0.9	-	1	1.1	mm
e	nominal pitch		-	-	0.65	-	mm
n ₂	actual quantity of termination		-	-	32	-	

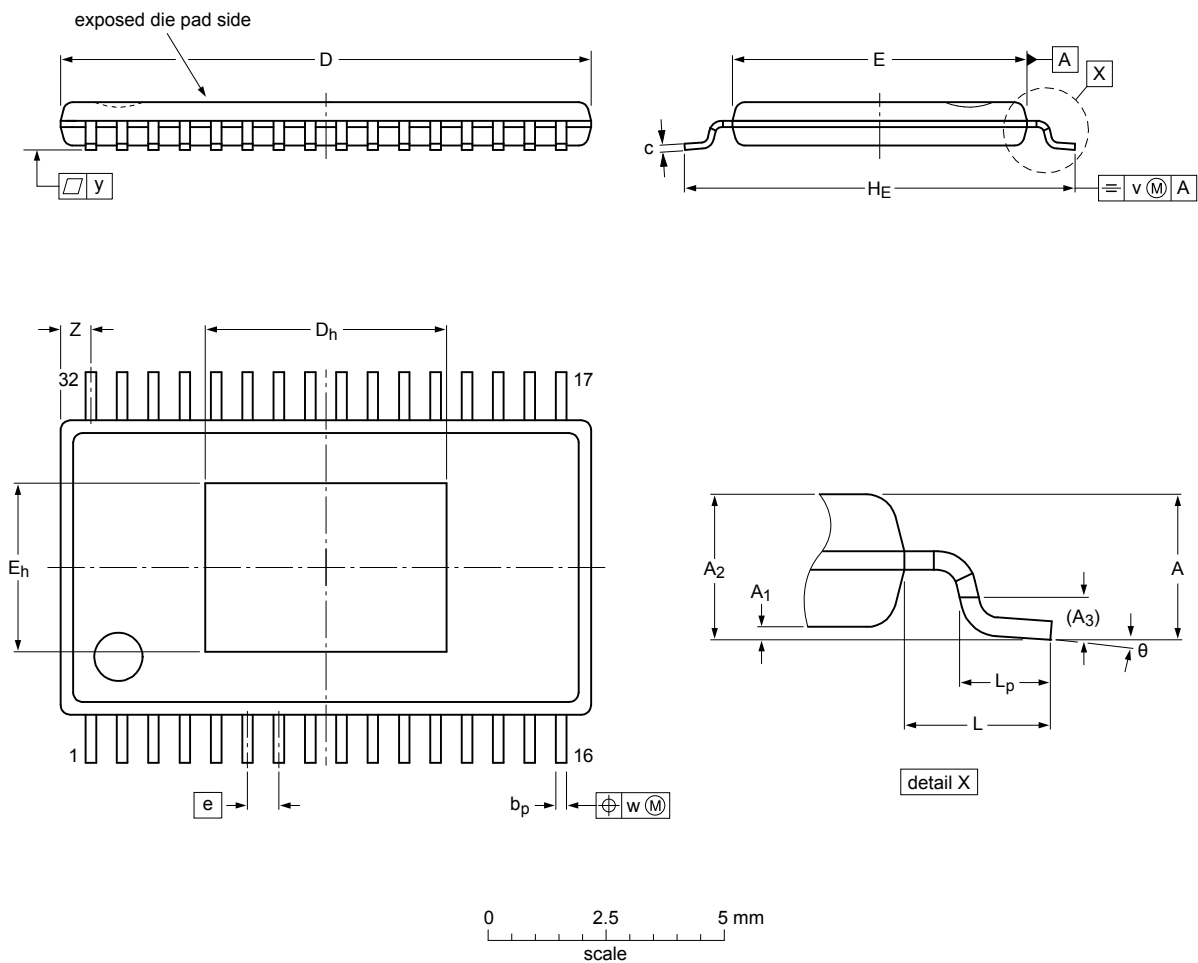


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2. Package outline

HTSSOP32: plastic thermal enhanced thin shrink small outline package; 32 leads;
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Dimensions: (mm are the original dimensions)

Unit ⁽¹⁾	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽²⁾	E _h	e	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ
max	1.10	0.15	0.95		0.30	0.200	11.1	5.1	6.2	3.6		8.3		0.750				0.78	8°
nom	1.00	0.10	0.90	0.25	0.22	0.127	11.0	5.0	6.1	3.5	0.65	8.1	1.0	0.625	0.20	0.10	0.10	0.63	4°
min	0.90	0.05	0.85		0.19	0.090	10.9	4.9	6.0	3.4		7.9		0.500				0.48	0°

- Note
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot1373-1_po

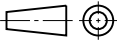
Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1373-1		MO-153				14-05-15- 14-05-20

Fig. 1. Package outline HTSSOP32 (SOT1373-1)

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3. Legal information

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